

2703 308 6916

\*\*\*\*\*  
\*\*\* RX REPORT \*\*\*  
\*\*\*\*\*

RECEPTION OK

TX/RX NO	7616
CONNECTION TEL	908 771 6159
CONNECTION ID	
START TIME	08/16(FR)19:34
USAGE TIME	06'22"
PGS.	18
RESULT	OK

SN 09/583,599

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re patent application of: Wang et al.

Serial No.: 09/583,599

Group Art Unit: 1741

Filed: May 31, 2000

Examiner: Tran, T.

Attorney Docket: 99A209

Title: Improved Acid Copper Electroplating Solutions

ASSISTANT COMMISSIONER FOR PATENTS  
Washington, D. C. 20231

S I R:

PETITION TO REVIVE AND  
RESPONSE TO OFFICE ACTION

In response to the Notice of Abandonment of April 9, 2002, Applicants hereby submit a Petition to Revive the above-referenced application, which was unintentionally abandoned. In support of the requested petition, Applicants submit the following amendment and remarks in response to the Office Action dated September 26, 2001 (Paper No. 6).

In the claims

Please cancel claims 9-10, 12, 15, 26-27, 29, 32, 47-48, 50 and 53.

Please amend claims 1, 6, 11, 13-14, 21, 23, 28, 30, 31, 39, 49 and 51-52 as follows:

1. (Amended) An acid copper electroplating composition comprising an aqueous solution of an acid and a copper salt, the improvement comprising the addition of at least one of a carrier compound; a water-soluble, mercapto-containing organic brightener compound; and a leveler compound which comprises an organic compound containing single or multiply positively charged centers; wherein said organic compound is selected from the group consisting of polyethylenimine, 80% ethoxylated; poly(allylamine); poly(allylamine hydrochloride); polyaniline, sulfonated, 5 wt. % in water, 75 mole % sulfonated; poly[bis(2-chloroethyl)ether-alt-